61°EX	
FORM PTO-1595-+ REC 05 - 1	3-2003 U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
1	A1-180 CIP US 1
I to the Honorabia's commissioner by Patents and Trad	
Name of conveying party(ies): 5-6-0	46151
Atsuhito Noda and Yoshihiro Tetsuka	Name: MOLEX INCORPORATED
Additional name(s) of conveying party(ies) attached? Yes X No	Internal Address: Thomas D. Paulius
3 Nature of conveyance:	
⊠ Assignment ☐ Merger	
Security Agreement Change of Name	Street Address: 2222 Wellington Court
Other	City: Lisle State: IL ZIP: 60532
Execution Date: April 3, 2003	Additional approximation of the first firs
Second Sub-Tipin 1, 2005	Additional name(s) & address(es) attached?  Yes X No
4. Application number(s) or patent number(s):	
If this document is being filed together with a new application, the execution date of the application is:	
A. Patent Application No.(s) 10/3725 865	B. Patent No.(s)
Additional numbers attached? Yes No	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: [1]
Name: MOLEX INCORPORATED	
Internal Address: Attention:	7. Total Fee (37 CFR 3.41) \$40.00
	☐ Enclosed
Thomas D. Paulius	Authorized to be charged to deposit account
	Additionated to be charged to deposit account
Street Address: 2222 Wellington Court	8. Deposit account number: 50-1873
_	
City: Lisle State: IL ZIP: 60532	
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9. Statement and signature.  To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original	
cocument.	
Chomas D. Paulius     April 30, 2003       Name of Person Signing     Signature     Date	
Name of Person Signing Signa	Total number of pages comprising cover sheet:
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Budget, Paperwork Reduction Project (6651-0011), Washington, D.C. 20503.	

1 05/12/2003 GTON11 00000\(\frac{1}{2}\)05 501873 10372865 03 FC:8021 40.00 CH

## ASSIGNMENT

Attorney Docket No.: A1-180 CIP 1 US

Serial No.: 10/372,865

Inventor(s):

Filing Date: February 24, 2003

Atsuhito Noda and Yoshihiro Tetsuka

Date of Execution of Application:

The undersigned hereby assigns to MOLEX INCORPORATED a Delaware Corporation, having its principal office in Lisle, Illinois (hereinafter referred to as "assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned discloses in an application for Letters Patent of the United States entitled:

## LOW-PROFILE CONNECTOR FOR CIRCUIT BOARDS

and identified as Attorney Docket No. A1-180 CIP 1 US in the Legal Department of Molex Incorporated, 2222 Wellington Court, Lisle, Illinois 60532, and in said patent application and any and all other applications, including United States, international and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension of such patents.

The undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee(s).

The undersigned hereby authorizes and requests the attorneys of record in said application to insert in this assignment the date of execution of said application, and further warrants that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

The undersigned hereby further agrees, upon the request, and at the expense of said assignee, its successors, legal representatives and assigns, to execute any and all divisional continuation and renewal or substitute applications for said invention or improvements, and any application for the reissue or extension or any request for the reexamination of any Letters Patents that may be granted upon said application, and any necessary oath or supplemental oath or affidavit or declaration relating thereto, that said assignee, its successors, legal representatives and assigns may deem necessary or expedient.

The undersigned further agrees upon the request of said assignee, its successors, legal representatives and assigns, in the event that said application or any continuing application thereof, or Letters Patent issued thereon, or any reissue or application for the reissue thereof, becomes involved in interference, reexamination or litigation in the courts, to cooperate to the best of my ability with said assignee, its successors, legal representatives and assigns in the matters of preparing the executing preliminary statements and other pleadings and documents and giving and producing evidence in support thereof including testimony in either oral or written form; and the undersigned still further agrees to perform upon such request any and all affirmative acts to obtain any said Letters Patent, and vest all rights therein hereby conveyed in the said assignee, its successors, legal representatives and assigns to the end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

PATENT REEL: 014047 FRAME: 0747

RECORDED: 05/06/2003

I hereby also assign to said assignee, its successors, legal representatives and assigns the entire right, title and interest in said invention or improvements for any and all foreign countries and the right of priority for patent and utility model applications in all countries arising under any applicable international convention for the protection of industrial property and/or any internal priority legislation of such countries, and I further agree upon the request of said assignee, its successors, legal representatives and assigns to execute any and all documents that shall be required to be executed in connection with any and all applications for foreign Letters Patent therefor, including the prosecution thereof and litigation relative thereto, and to execute any and all documents necessary to invest title in said foreign applications and patents in said assignee.

IN WITNESS WHEREOF, I have executed this instrument on the date indicated below:

Atsuhito Noda Date

Toshihiro Tersuka '03/04/25

Date

Yoshihiro Tetsuka

PATENT REEL: 014047 FRAME: 0748